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(54) **MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD, AND RESIN COMPOSITION FOR FILLING THROUGH-HOLE**

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(56)

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(57) **ABSTRACT**

A multilayer printed wiring board is composed of a substrate provided with through-holes, and a wiring board formed on the substrate through the interposition of an interlaminar insulating resin layer, the through-holes having a roughened internal surface and being filled with a filler, an exposed part of the filler in the through-holes being covered with a through-hole-covering conductor layer, and a viahole formed just thereabove being connected to the through-hole-covering conductor layer. Without peeling between the through-holes and the filler, this wiring board has a satisfactory connection reliability between the through-holes and the internal layer circuit and provides a high density wiring.

**86 Claims, 8 Drawing Sheets**

